

Please amend claim 1 as follows:

1. (Amended) [Carrier] A carrier member composed of a ceramic for electronic components having at least two metallic contact surfaces [(2)] electrically insulated from one another, said [whereby the] contact surfaces [are arranged] being disposed on a common plane of the carrier member, [characterized in that] further metallized surfaces [(3) are located] disposed on at least one surface of the carrier member that does not proceed parallel to the common plane of the contact surfaces [(2), whereby a] and respective conductive connections between said metallized surfaces and said [surface is conductively connected to one of the] contact surfaces.

Please amend claim 2 as follows:

2. (Amended) [Carrier] A carrier member according to claim 1, [characterized in that] wherein the carrier member comprises a base and [roof element (13), whereby] an inductive component [(17) is arranged] disposed on [the] an inside surface of the base [roof element (11)].

Please amend claim 3 as follows:

3. (Amended) [Carrier] A carrier member according to claim 1 [or 2, characterized in that] wherein the surfaces that do not proceed parallel to the common plane of the contact surfaces [(2)] and on which the metallized surfaces [(3)] are located, proceed at an angle of 90° relative to the common plane of the contact surfaces [(2)].

Please amend claim 4 as follows:

- (Amended) [Carrier] A carrier member according to at least one of the claims] claim 1 [through 3, characterized in that the carrier member comprises] comprising two walls [(12)] proceeding at an angle of 90° relative to the common plane of the contact surfaces [(2)], a [roof

element (13) that is arranged] base disposed perpendicular to the walls and parallel to the common plane of the contact surfaces [(2)], and two end walls [(5)] that are [arranged] perpendicular to the base [roof element] and the walls.

5 Please amend claim 5 as follows:

5. (Amended) [Carrier] A carrier member according to [at least one of the claims] claim 1 [through 4, characterized in that] channel-shaped depressions [(4) are] situated between the metallic contact surfaces [(2)] and the metallized surfaces [(3)], [whereby] the channel-shaped depressions  
10 [are] not being metallized.

Please amend claim 6 as follows:

6. (Amended) [Carrier] A carrier member according to claim 5, [characterized in that] wherein said channel-shaped depressions [(4)] are [arranged] disposed on the common plane of the contact surfaces [(2)] and  
15 comprising further channel-shaped depressions [(4) are located] disposed on the planes that do not proceed parallel to the common plane of the contact surfaces, [whereby these] said further channel-shaped depressions [(4)] arranged on various planes [form] forming channel edges [(15)].

Please amend claim 7 as follows:

20 7. (Amended) [Carrier] A carrier member according to [at least one of the claims 1 through] claim 6, comprising [characterized in that] a lead that [(7)] is electrically conductively connected to one of said [a] metallized surfaces [surface (3)].

Please amend claim 8 as follows:

8. (Amended) [Carrier] A carrier member according to [at least one of the claims 1 through] claim 7, [characterized in that the] wherein one of said channel edges [edge] guides [a] said lead [(7)] such that the lead is mechanically localized [experiences a mechanical localization] in the channel edges [(15)].

Please amend claim 9 as follows:

9. (Amended) [Carrier] A carrier member according to claim 8, [characterized in that] wherein the lead [(7)] guided by the channel edge [(15)] is conductively connected to one of said [a] metallized [surface (3)] surfaces immediately adjacent to [the] a corresponding channel-shaped depression.

Please amend claim 10 as follows:

10. (Amended) [Carrier] A carrier member according to [at least one of the claims] claim 1 [through 9, characterized in that the co-planarity of the plane-parallel] contact surfaces [(2) amounts to] have a co-planarity of less than 100 μm, whereby the co-planarity is [the] a maximum spacing from a plane that lies parallel to the contact surfaces [(2)] and that has been calculated from the individual heights of the contact surfaces [(2)].

20 Please amend claim 11 as follows:

11. (Amended) [Carrier] A carrier member according to [at least one of the claims] claim 1 [through 10, characterized in that a roof element (1) is provided, the base (2) is disposed parallel to the common plane of the contact surfaces (2) is present, and a conical trustum (6) is arranged disposed on [the] an inside surface of the base and projecting toward an [roof element (11) in the direction of the] interior of said carrier member [(6)].

Please amend claim 12 as follows:

12. (Amended) [Carrier] A carrier member according to [at least one of the claims] claim 1 [through 11, characterized in that a roof element (13)] comprising a base proceeding parallel to the common plane of the contact surfaces [(2) is present], and a core [(9)] with a winding [(14) is arranged ] disposed on [the] an inside surface of the [roof element (11) in the] base in a direction [of the] toward an interior of said carrier member.

✓ Please cancel claims 13, 14 and 15.

✓ Please add the following new claim 16:

10 16. A method for manufacturing an electronic component, comprising the steps of:

providing a carrier member composed of ceramic having at least two metallic contact surfaces that are electrically insulated from one another, said contact surfaces being disposed on a common plane of the carrier member, and said carrier member having further metallized surfaces disposed on at least one surface of said carrier member that does not proceed parallel to said common plane of said contact surfaces, and having respective conductive connections between said metallized surfaces and said contact surfaces, and said carrier member having an inside surface;

fastening an inductive component on said inside surface of said carrier member, said inductive component having wires proceeding therefrom;

producing channel edges between said metallic contact surfaces in said common plane of said carrier member;

guiding said wires of said inductive component over said channel edges;